



Materials Declaration

| | |
|------------------|-------------------------|
| Package | SC 70-ISOLATED BACKSIDE |
| Body Size | -- |
| LeadCount | 3 |
| Option | Pb-Free |

Molding Compound

| Item | % of Compound | Weight (g) | PPM |
|--------------|---------------|------------|--------|
| SiO2 Filler | 77.3 | 2.19 E-03 | 397383 |
| Epoxy Resin | 10.2 | 2.89 E-04 | 52436 |
| Phenol Resin | 10.0 | 2.83 E-04 | 51408 |
| Sb2O3 | 1.5 | 4.25 E-05 | 7711 |
| Carbon Black | 1.0 | 2.83 E-05 | 5141 |

Leadframe

| Item | % of Leadframe | Weight (g) | PPM |
|------|----------------|------------|--------|
| Fe | 58.7 | 1.29 E-03 | 234407 |
| Ni | 40.9 | 9.00 E-04 | 163452 |
| Mn | 0.4 | 9.46 E-06 | 1718 |
| Si | 0.1 | 1.32 E-06 | 240 |

Internal Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|------|--------------|------------|-----|
| Ag | 100.0 | 4.40 E-06 | 799 |

External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|------|--------------|------------|-------|
| Sn | 100.0 | 2.00 E-04 | 36331 |

Bond Wires

| Item | % of Wire | Weight (g) | PPM |
|------|-----------|------------|------|
| Au | 99.9 | 3.00 E-05 | 5450 |

Chip

| Item | % of Chip | Weight (g) | PPM |
|------|-----------|------------|-------|
| Si | 100.0 | 2.10 E-04 | 38147 |

Die Attach

| Item | % of Die Attach | Weight (g) | PPM |
|-------------------------|-----------------|------------|------|
| Epoxy resin | 46.0 | 1.38 E-05 | 2507 |
| Silicon dioxide | 46.0 | 1.38 E-05 | 2507 |
| Curing agent & hardener | 8.0 | 2.00 E-06 | 363 |

Molding Compound

| Item | PPM | Method |
|------|---------------|----------------------------------|
| Pb | None Detected | US EPA 3052. ICP-OES |
| Cd | None Detected | US EPA 3052. ICP-OES |
| Hg | None Detected | US EPA 3052. ICP-OES |
| Cr+6 | None Detected | US EPA 3060A & 7196A. UV-VIS |
| PBB | None Detected | Analysis was performed by GC/ MS |
| PBDE | None Detected | Analysis was performed by GC/ MS |

Die Attach Paste

| Item | PPM | Method |
|------|---------------|----------------------------------|
| Pb | None Detected | US EPA 3052. ICP-OES |
| Cd | None Detected | US EPA 3052. ICP-OES |
| Hg | None Detected | US EPA 3052. ICP-OES |
| Cr+6 | None Detected | US EPA 3060A & 7196A. UV-VIS |
| PBB | None Detected | Analysis was performed by GC/ MS |
| PBDE | None Detected | Analysis was performed by GC/ MS |

Package Totals

| Weight (g) | PPM |
|------------------|----------------|
| 5.50 E-03 | 1000000 |

Note: The information provided in this declaration are true to the best of ADI's knowledge
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

10/2/06





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| LeadCount | 3 |
| Option | SnPb |

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Internal Leadframe Plating

| | % of Plating | Weight (g) | PPM |
|----|--------------|------------|-----|
| Ag | 100.0 | 4.40 E-06 | 799 |

External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|------|--------------|------------|-------|
| Sn | 85.0 | 1.70 E-04 | 30881 |
| Pb | 15.0 | 3.00 E-05 | 5450 |

Bond Wires

| | % of Wire | Weight (g) | PPM |
|----|-----------|------------|------|
| Au | 99.9 | 3.00 E-05 | 5450 |

Chip

| | % of Chip | Weight (g) | PPM |
|----|-----------|------------|-------|
| Si | 100.0 | 2.10 E-04 | 38147 |

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